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ELECTRONIC CIRCUITS

Volume 3

Analysis and Design of Integrated Electronic Circuits

SECOND EDITION

PAUL M. CHIRLIAN

Stevens Institute of Technology



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Preface

This is the second edition of an undergraduate textbook that covers the core topics in electronics that all electrical engineers should know. The book has been upgraded to reflect changes in technology and in electrical engineering curricula. This text concentrates mainly on electronic circuits, so that changes in circuitry, rather than in device structure, are stressed. The philosophy remains the same: It is important that the electrical engineer have a thorough understanding of the analytic tools needed to analyze and design electronic circuits. Therefore, topics such as modeling still are discussed in detail. The electrical engineer must be better educated than the technician, and so the mathematical viewpoint of the first edition has been carried over into the second edition.

The following are some of the principal changes in the second edition.

A discussion of high-speed TTL has been included in Chapter 9, and the discussion of STTL has been extended.

A thorough discussion of the use of mixed-logic representation has been integrated at appropriate points throughout the book. In addition, dependency notation is discussed in detail.

The effects of poor feedback design are covered in Chapter 16. In particular, the relation between poor design and the so-called “transient intermodulation distortion” is considered.

Switched-capacitor filters are discussed. There is sufficient detail included here so that the reader will know how to design simple switched-capacitor filters. Circuits that minimize the effects of stray capacitance are considered. The z transform is not used in this discussion because z transforms are not presumed to be a prerequisite for a course in which this book is used. However, the need for the use of z transforms by the serious worker in the switched-capacitor field is discussed. The periodic frequency response of switched-capacitor filters is presented, and the use of analog prefilters is considered.

The chapter on microprocessors has been removed. Most electrical engineering curricula now include courses on microprocessors so that it is not necessary to include

this material in the electronic-circuits courses. Because the material is now typically covered in communication courses, the chapter on modulation and demodulation has also been removed.

The notation used in the figures has been changed. The polarity of the voltages is no longer designated by an arrow. Instead, only plus and minus signs are used.

Finally, the second edition has been checked very carefully for errors. After considerable class testing and detailed study, a number of errors have been located and removed from this second edition. We have made every effort to make the text error-free.

Analysis and Design of Integrated Electronic Circuits continues to provide students at the junior and senior levels with a thorough understanding of most electronic circuits and the procedures used to analyze and design them. Integrated circuits and their applications are stressed. However, the use of discrete devices such as junction transistors and FETs is also considered. Many numerical examples of both analysis and design are incorporated throughout the book. It is hoped that, from these, the student will develop a general design philosophy that can be used with all electronic circuit designs.

This is an electronic circuits text and, therefore, there will be no detailed discussion of semiconductor physics. However, the first four chapters of the book do present enough information in order that a basic understanding of semiconductor electronic devices can be obtained.

In Chapters 1 through 3, the physics and basic principles of semiconductors, p - n junction diodes, and transistors are discussed. The discussion of physics is brief. It is sufficiently detailed, however, so that the reader will understand the basics. Such things as junction capacitance, switching speed, characteristics, and ratings are discussed in detail.

The fabrication of integrated circuits is discussed in Chapter 4. The problems encountered are considered, and all types of fabrications are discussed. In Chapter 5 the graphical analysis techniques are presented. Because of the wide use of direct coupled circuits, their graphical analysis is considered in detail.

Modeling is discussed in Chapters 6 and 7. Chapter 6 concerns itself with linear models. Since the hybrid- π model for the transistor is used throughout the book, this model is stressed. However, the h -parameter model is also thoroughly developed and related to the hybrid- π model. The linear high-frequency model for the FET is also developed, and some basic amplifier circuits are also studied here. Pulse and large-signal models are the topics of Chapter 7. The Ebers and Moll model for the transistor and low-speed models for the FET are developed. Next, high-speed models are obtained. The use of approximate models is discussed.

Chapters 8 through 11 are concerned with the basic ideas and circuits of digital systems. In Chapter 8, fundamental ideas such as number systems and gates are considered, and switching functions and Karnaugh maps are studied. All the commonly used logic families are discussed in Chapter 9. The electrical analysis of the various families is discussed there in great detail. Sequential circuits are the topic of Chapter 10. The design of both synchronous and asynchronous circuits is discussed in considerable detail. Various devices such as registers and counters are considered from both a design and an applications viewpoint. Memories are presented in Chapter 11. All of the semiconductor memories are thoroughly considered. There is also a discussion of CCD and magnetic bubble memories.

Broadband amplifiers are discussed in Chapter 12. This chapter starts with a general discussion of amplification. Next, single-stage amplifiers are studied, and finally, the design of multistage amplifiers is discussed. Transient and steady state response are considered. The chapter concludes with a discussion of noise. Operational amplifier applications are presented in great detail in Chapter 13. Many analog and digital circuits are discussed here to provide the reader with a thorough understanding of how operational amplifier circuits perform and how such circuits can be designed.

The actual circuitry within the operational amplifier chip is discussed in Chapter 14. Techniques for analyzing these circuits are presented. Small-signal and bias analyses are presented in a thorough analysis of the operational amplifier. Power amplifiers are discussed in Chapter 15. Transformerless push-pull amplifiers are stressed here and graphical analysis and design techniques are developed.

Feedback amplifiers are thoroughly discussed in Chapter 16. A rigorous, accurate discussion is given here. Although the mathematics level is kept suitable for a junior or senior level course, sufficient material is included, so the student understands what he or she is doing. The design of feedback systems using the Nyquist criterion and frequency compensation is discussed in great detail. Bandpass amplifiers are the topic of Chapter 17. Active filters and conventional tuned amplifiers are studied, Butterworth and Chebyshev frequency responses are developed, and the superheterodyne receiver is discussed.

Both sinusoidal and nonsinusoidal oscillators are studied in Chapter 18. Topics such as linear and nonlinear operation and frequency stabilization are also presented. Power supplies are considered in Chapter 19. Rectifiers, filters, and voltage regulators are studied. The design of switching regulators is considered in detail.

There are numerical examples amply distributed throughout the book. In addition, a large selection of homework problems is included at the end of each chapter. The instructor need not follow the order of these chapters exactly. For instance, the entire unit of Chapters 8 through 11 could be discussed toward the end of the book.

I would like to express my thanks to my colleagues Professors Alfred C. Gilmore, Jr., Stanley Smith, Edward Peskin, and Yusuf Z. Efe for the many helpful discussions during the writing of the first edition of this book, and also to the reviewers Professors J. D. Bargainer, A. J. Broderson, R. E. Lee, and J. H. Mulligan, Jr., for their many helpful comments on it.

I wish to express my gratitude to Professor Gilmore for his contributions to the second edition as well as the first and to the reviewers of the manuscript of the second edition, who read it with extreme care and made many helpful comments: David Greve, Carnegie Mellon University; Charles Nelson, CSU/Sacramento; Bruce Johnson, University of Nevada/Reno; David Soldan, Oklahoma State University; C. A. Ramblings, Southern Illinois University; Sidney Soclof, CSU/Los Angeles; David Green, University of Alabama/Birmingham; Russell Krackhardt, Worcester Polytechnic Institute; James Bargainer, Baylor University; and Giles Willis, Baylor University. I again express my loving and heartfelt thanks to my wife Barbara for her editing of the text and her encouragement.

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Chapter 1

Semiconductors and the p - n Junction Diode

Modern semiconductor devices have profoundly changed electronics. A device as simple as a radio has changed from a bulky vacuum tube device to the portable “transistor radio.” The modern powerful digital computer would be impractical were it not for integrated circuit technology, which allows thousands of devices to be fabricated on a single chip. Indeed, complete small computers can be built on a single small chip. These microcomputers not only will be used in sophisticated electronic devices, but will find ever increasing use in “commonplace” things. For instance, these small computers can control the engine of an automobile so that its efficiency is greatly improved. They can also ensure the safe operation of a railroad or monitor the recovery room of a hospital.

In this book we shall consider electronic circuits. We shall start with a basic discussion of how electronic devices operate. Fabrication methods, including those for integrated circuits, will also be discussed here. After this we shall study the fundamental ideas used in building electronic circuits and the means for analyzing them. Then, the analysis and design of basic circuits will be discussed. As we progress through the book, the complexity of the circuits will be increased.

Integrated circuit applications will be stressed in this book. However, there are cases where discrete devices are used in practical circuits and these will be discussed when appropriate. A well-educated electrical engineer must understand the operation of integrated circuits thoroughly. Of course, integrated circuits consist of the interconnection of individual devices. Thus, we do not take the viewpoint that a study of discrete devices is unnecessary for those who will work with integrated circuits. For instance, the effect of temperature on the behavior of an individual transistor must be known if the effect of temperature on the behavior of an LSI (large-scale integration) chip, containing many of these transistors, is to be thoroughly understood. In a similar way, the high-frequency model for a discrete transistor is used to obtain the frequency response of an integrated circuit amplifier containing many of these transistors. Thus, we cannot ignore those topics in discrete circuits that improve our understanding of integrated circuits.

Many design examples will be incorporated in the book. The object of these examples will be twofold. They will serve to teach the design of the particular type of circuit under consideration as well as to illustrate some ideas common to many types of design.

We shall start with a basic discussion of semiconductors.

1-1. SEMICONDUCTORS

Modern electronic devices are composed of *semiconductor* materials. In this section we shall discuss some basic ideas of the physics of semiconductors. Subsequently, we shall consider how semiconductors are used in electronic devices. Usually, the atoms of semiconductors that are used in devices are arranged in a regular array called a *crystal*. Such an array for the semiconductor silicon is shown diagrammatically in Fig. 1-1. Materials of valence 4 form such an array. That is, they have four valence electrons, each of which enters into a *covalent bond*, or *electron-pair bond*, with a valence electron of a neighboring atom.

Let us discuss electrical conduction in such a crystal. If each valence electron is bound in its covalent bond pair, then no conduction can take place. If there is to be conduction, then some of the valence electrons must acquire sufficient energy to break their covalent bonds and become free to travel throughout the material. Such electrons are called *free electrons*. Let us consider, in greater detail, the process whereby valence electrons break their bonds.

In a single isolated atom, the electrons cannot possess arbitrary amounts of energy. They can only possess certain allowed energy levels called *discrete energy levels*. There is a maximum number of electrons (which varies from level to level) which can occupy a given energy level. Actually the state of the electron is characterized by a quantum number and no two electrons of an atom can have the same quantum number. When the number of electrons occupying a level is equal to the maximum for that level, then the level is said to be *filled*.

When two atoms are brought together, the energy levels *split*. That is, the two identical levels in each atom now become two distinct new levels, which are very close to the original one. When more atoms are brought together, the energy levels split further.

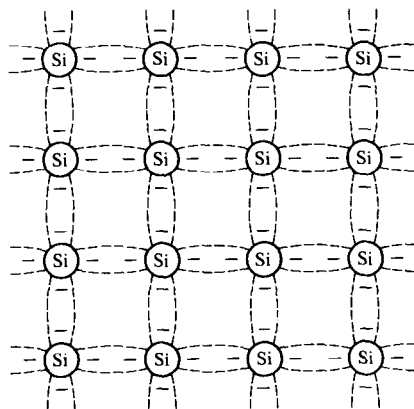


Figure 1-1 A symbolic representation of a silicon crystal array.